

Product Description: QSFP-DD Assembly, Stacked 2x1, Closed Top Part Number: 2040588113

Status: Active

Series Number: 204058

Product Category: High-Speed I/O

Connectors

Documents & Resources

Drawings

Drawing 2040588113_sd.pdf

3D Models and Design Files

3D Model 2040588113_stp.zip

Electrical Model Document 2040586110LP-000.pdf Electrical Model Document 2040586110UP-000.pdf

S-Parameter Model 2040586110-000.zip

Specifications

Application Specification 2040580004-000.pdf Product Specification 2040580001-PS.pdf Test Summary 2040580001-TS-000.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	©
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2023)3788-DC (14 Jun 2023)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C

- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	Active
Category	High-Speed I/O Connectors
Series	204058
Description	QSFP-DD Assembly, Stacked 2x1, Closed Top
Application	Module-to-Board
Component Type	Receptacle
Product Family	QSFP-DD Interconnect System and Cable Assemblies
Product Name	QSFP-DD
Туре	Pluggable
UPC	191130500024

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	2.0A
Data Rate	56.0 Gbps
Grounding to Panel	Yes
Shield Type	EMI Fingers
Shielded	Yes
Voltage - Maximum	30V AC (RMS) / 42V DC

Physical

Circuits (Loaded)	152
Circuits (maximum)	152

Color - Resin	Black
Durability (mating cycles max)	250
Flammability	94V-0
Gender	Female
Keying to Mating Part	None
Lock to Mating Part	Yes
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Matte Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	43.000/g
Number of Rows	2
Orientation	Right Angle
Packaging Type	Tray
Panel Mount	Spring Tabs
PC Tail Length	1.70mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness - Recommended	1.57mm
Pitch - Mating Interface	0.80mm
Plating min - Mating	0.760µm
Plating min - Termination	0.760µm
Polarized to Mating Part	Yes
Polarized to PCB	Yes
Ports	2
Temperature Range - Operating	-25° to +65°C
Termination Interface Style	Through Hole - Compliant Pin

Mates With / Use With

Mates with Part(s)

Description	Part Number
QSFP-DD-to-QSFP-DD Passive Cable Assemblies, 56 Gbps	<u>201591</u>
QSFP Cable Assemlies	<u>74757</u>

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